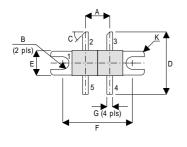
TetraFET

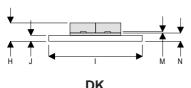
D2208UK



ROHS COMPLIANT METAL GATE RF SILICON FET

MECHANICAL DATA





PIN 1	SOURCE (COMMON)	PIN 2	DRAIN 1
PIN 3	DRAIN 2	PIN 4	GATE 2

PIN 5 GATE 1

DIM		Tol.	Inches	Tal	
DIN	mm	101.	Inches	Tol.	
Α	6.45	0.13	0.254	0.005	
В	1.65R	0.13	0.065R	0.005	
С	45°	5°	45°	5°	
D	16.51	0.76	0.650	0.03	
Е	6.47	0.13	0.255	0.005	
F	18.41	0.13	0.725	0.005	
G	1.52	0.13	0.060	0.005	
Н	4.82	0.25	0.190	0.010	
1	24.76	0.13	0.975	0.005	
J	1.52	0.13	0.060	0.005	
Κ	0.81R	0.13	0.032R	0.005	
М	0.13	0.02	0.005	0.001	
Ν	2.16	0.13	0.085	0.005	

ONS COMPLIANT METAL GATE RESILICON FET

GOLD METALLISED MULTI-PURPOSE SILICON DMOS RF FET 40W – 12.5V – 500MHz PUSH–PULL

FEATURES

- SIMPLIFIED AMPLIFIER DESIGN
- SUITABLE FOR BROAD BAND APPLICATIONS
- VERY LOW C_{rss}
- SIMPLE BIAS CIRCUITS
- LOW NOISE
- HIGH GAIN 10 dB MINIMUM

APPLICATIONS

• HF/VHF/UHF COMMUNICATIONS from 1MHz to 1 GHz

ABSOLUTE MAXIMUM RATINGS (T_{case} = 25°C unless otherwise stated)

P _D	Power Dissipation	134W
BV _{DSS}	Drain – Source Breakdown Voltage *	40V
BV _{GSS}	Gate – Source Breakdown Voltage *	±20V
I _{D(sat)}	Drain Current *	16A
T _{stg}	Storage Temperature	–65 to 150°C
Ţj	Maximum Operating Junction Temperature	200°C

* Per Side

Semelab PIc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.



ELECTRICAL CHARACTERISTICS (T_{case} = 25°C unless otherwise stated)

Parameter		Test Conditions		Min.	Тур.	Max.	Unit
	PER SIDE						
BVaca	Drain-Source	$V_{GS} = 0$	I _D = 10mA	40			V
BV _{DSS}	Breakdown Voltage	VGS - 0	D = 1011A	40			Ň
	Zero Gate Voltage	V _{DS} = 12.5V	V _{GS} = 0			0	
DSS	Drain Current					8	mA
I _{GSS}	Gate Leakage Current	$V_{GS} = 20V$	$V_{DS} = 0$			4	μΑ
V _{GS(th)}	Gate Threshold Voltage *	I _D = 10mA	$V_{DS} = V_{GS}$	0.5		7	V
9 _{fs}	Forward Transconductance *	V _{DS} = 10V	I _D = 1.6A	1.44			S
	TOTAL DEVICE						
G _{PS}	Common Source Power Gain	P _O = 40W		10			dB
η	Drain Efficiency	V _{DS} = 12.5V	I _{DQ} = 1.6A	40			%
VSWR	Load Mismatch Tolerance	f = 500MHz		20:1			—
PER SIDE							
C _{iss}	Input Capacitance	$V_{DS} = 0$ V_{GS}	_S = -5V f = 1MHz			96	pF
C _{oss}	Output Capacitance	$V_{DS} = 12.5V V_{GS}$	$_{\rm S} = 0$ f = 1MHz			80	pF
C _{rss}	Reverse Transfer Capacitance	$V_{DS} = 12.5V V_{GS}$	f = 0 f = 1MHz			8	pF

* Pulse Test: Pulse Duration = 300 μs , Duty Cycle $\leq 2\%$

HAZARDOUS MATERIAL WARNING

The ceramic portion of the device between leads and metal flange is beryllium oxide. Beryllium oxide dust is highly toxic and care must be taken during handling and mounting to avoid damage to this area.

THESE DEVICES MUST NEVER BE THROWN AWAY WITH GENERAL INDUSTRIAL OR DOMESTIC WASTE.

THERMAL DATA

R _{THj-case}	Thermal Resistance Junction – Case	Max. 1.3°C / W
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